

### 4.0x4.0mm RIGHT ANGLE SURFACE MOUNT **LED LAMP**

Part Number: KA-4040QBS-D Blue



**ATTENTION** OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE **DEVICES** 

#### **Features**

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package : 500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

#### Description

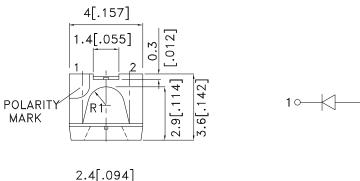
The Blue source color devices are made with InGaN Light Emitting Diode.

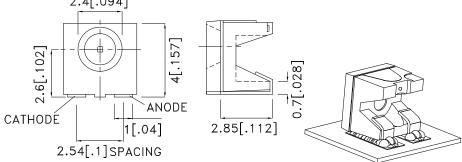
Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

## **Package Dimensions**





- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
   The device has a single mounting surface. The device must be mounted according to the specifications.

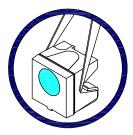
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### **Handling Precautions**

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





3. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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## **Selection Guide**

Part No.	Dice	Dice Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KA-4040QBS-D	Blue (InGaN)	Matan Class	110	220	120°
		Water Clear	110*	220*	

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
  2. Luminous intensity/ luminous Flux: +/-15%.
  \*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.		Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue	468	460*		nm	IF=20mA
λD [1]	Dominant Wavelength	Blue	470	465*		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue	2	5		nm	IF=20mA
С	Capacitance	Blue	10	00		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Blue	3.	3	4	V	IF=20mA
lr	Reverse Current	Blue			50	uA	VR=5V

#### Notes:

- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

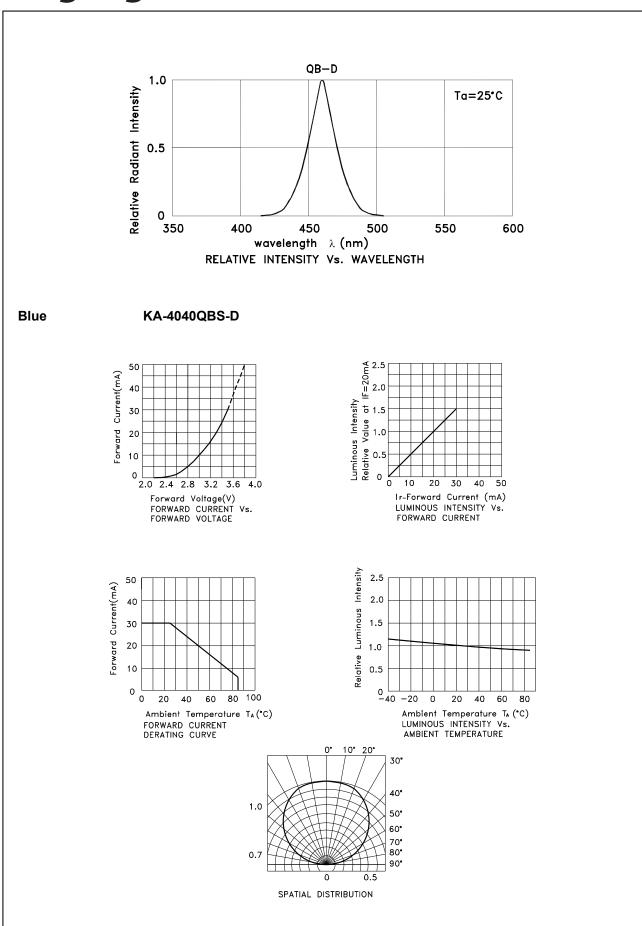
### Absolute Maximum Ratings at TA=25°C

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Parameter	Blue	Units			
Power dissipation	120	mW			
DC Forward Current	30	mA			
Peak Forward Current [1]	150	mA			
Reverse Voltage	5 V				
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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<sup>\*</sup> Wavelength value is traceable to the CIE127-2007 compliant national standards.

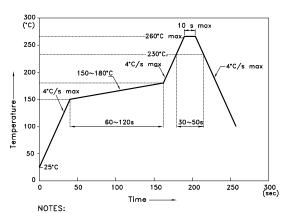


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### **KA-4040QBS-D**

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



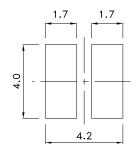
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

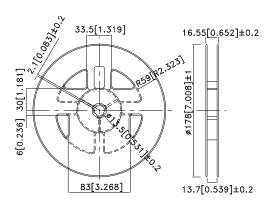
  3.Number of reflow process shall be 2 times or less.

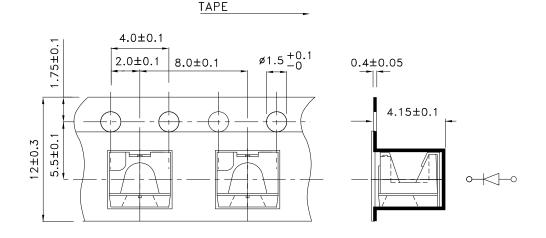
**Recommended Soldering Pattern** (Units: mm; Tolerance: ± 0.1)



## **Tape Dimensions** (Units : mm)

### **Reel Dimension**

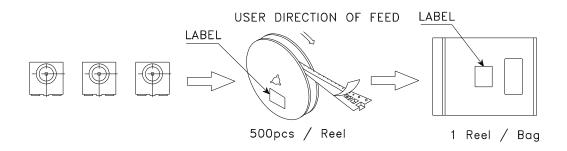


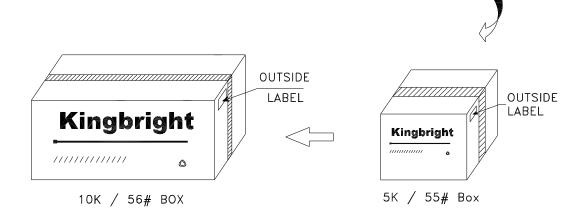


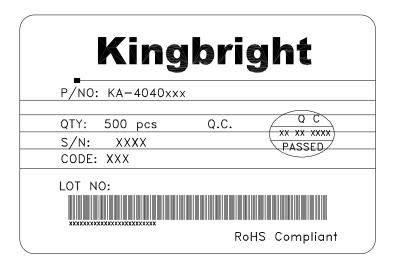
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### **PACKING & LABEL SPECIFICATIONS**

### **KA-4040QBS-D**







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